

WHAT IS CLAIMED IS:

3 1. A die pad configuration for an integrated circuit having an integrated circuit die, the  
4 die pad comprising:

5 a plurality of die pad regions for supporting the integrated circuit die, each die pad  
6 region having an area associated therewith, the die pad regions being arranged in a spaced  
7 apart relationship with respect to the die, the total area of the plurality of die pad regions  
8 being at most equal to fifty percent (50%) of the area of the die.

9 2. The die pad configuration of claim 1, wherein the plurality of die pad regions include  
10 four die pad regions.

11 3. The die pad configuration of claim 2, wherein the four die pad regions are spaced  
12 apart such that they are each proximate to a corner of the die.

13 4. The die pad configuration of claim 3 wherein the the total area of the four die pad  
14 regions is about 0.32 of the area of the die.

15 5. The die pad configuration of claim 1, wherein the plurality of die pad regions include  
16 two die pad regions.

17 6. The die pad configuration of claim 5, wherein the two die pad regions are spaced  
18 apart such that they are each proximate to an opposing edge of the die.

1 7. The die pad configuration of claim 6 wherein the area of the two die pad regions is  
2 about 0.42 of the area of the die.

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4 8. A die pad for an integrated circuit having an integrated circuit die, the die pad  
5 comprising a support portion for supporting the integrated circuit die, the support portion  
6 having a plurality of regions of relief therein, the relief regions being arranged in a spaced  
7 apart relationship with respect to the die, the support portion having a total area being at  
8 most equal to forty percent (40%) of the area of the die.

9 9. The die pad of claim 8, wherein the plurality of relief regions include four  
10 rectangular regions.

11 10. The die pad of claim 9, wherein the four relief regions are spaced apart such that they  
12 are each proximate to a corner of the die.

13 11. The die pad configuration of claim 8, wherein the plurality of relief regions include  
14 two rectangular regions.

1 12. The die pad of claim 10, wherein the two relief regions are spaced apart such that  
2 they are each proximate to an opposing edge of the die.